

3D Electronics Technical Specification

Layer	1-24
Min Line/Space on inner layer	0.075 mm/0.075mm (H OZ)
Min Line/Space on outer layer	0.1/0.1mm (1 OZ)
Board Thickness	0.2 ~ 3.2mm (8 ~ 126mil)
Copper Thickness	H~10OZ
Min. Hole Diameter	0.2mm
Hole Diameter Tolerance	± 0.025mm
Tolerance for hole position	±0.075 mm
Drilled long slot size (Min.)	0.5mm
Shape tolerance for drilled long slot	Width tolerance: +/-0.05mm Length tolerance: +/-0.05mm
Long slot position tolerance	+/-0.075mm
Hole distance (different nets)	MIN : 0.5mm
Hole wall copper thickness (via)	≥25um
Average copper thickness in holes	30um
Layer Misalignment	0.075mm
Hole position precision on outer pattern (Min.)	±0.075 mm
Tolerance from pattern to pattern (Min.)	±0.05mm
Min. Misalignment for solder mask	±0.035mm
Solder mask thickness	Min : 10um(on line) 5um (on shoulder edge)
Min. Solder mask bridge width	0.08mm
Hole diameter for plugged hole	0.2mm~0.65mm
Tin thickness for HASL	1~40um
Nickel thickness for immersion gold	3~8um
Gold thickness for immersion gold	0.05~0.1um
OSP thickness	0.2~0.4um
Surface Treatment	Hot Air leveling (HASL), HASL Lead-free, Immersion Gold, Plated Hard Gold, OSP (Organic Solder Protection), Immersion Silver, Flash Gold
Contour Tolerance	±0.1mm
Min Routed arc for inner angle	0.4mm
Min. distance from pattern to routed edge	0.25mm

V Cut Angle:	15°/25°/30°/45°/60°
Angle Tolerance for V-Cut	±5°
Board Thickness for V-Cut	0.3mm~ 2.4 mm
E-Test condition:	50-300V (Typical: 250V)
Isolation Resistance:	2MΩ-100MΩ (Typical: 20MΩ)
Conductive Resistance:	50Ω
Test Point Diameter:	≥0.2mm